Customer Information Notification

202605013I : PF53xx Data Sheet Update Rev 7.0 with New PF530xB Product Offerings and Technical Clarifications / Corrections

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 11, 2026 **Effective Date:** Sep 12, 2026

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Management summary

PF53xx Data Sheet Update Rev 7.0 with New PF530xB Product Offerings and Technical Clarifications / Corrections

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[ ]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[ ]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[ ]Wafer Fab Location	[ ]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage

[ ]Firmware [X]Other: Data Sheet Update (New Orderable Part Numbers and Technical Clarifications / Corrections)

Notification Overview

Description

NXP Semiconductors announces a data sheet update to revision 7.0 for the PF5300, PF5301, and PF5302 Power Management IC Products associated with this notification. The data sheet update includes new product offerings (PF53 B revision / PF530xB) with design and package enhancements, as well as technical clarifications and corrections.

The new PF53 B revision part numbers implement PFM operation to improve power efficiency / reduce power loss during standby mode. In addition, the PF53 B product package incorporates a minimum wettable flank height of 100 µm to improve soldering inspection reliability at Automated Optical Inspection (AOI).
PF530xB parts are recommended for new / future designs.

** Existing PF530xA products are not affected by the design or package enhancement changes. No design or package modifications have been made to PF530xA devices. All design and package changes are specific to the new enhanced PF530xB product offerings **

New PF5300_PF5301_PF5302 data sheet revision 7.0 is attached to this notification and can be found at the NXP site:
https://docs.nxp.com/bundle/PF5300_PF5301_PF5302/page/topics/overview.html

Please see the attached documents for additional details, including the revision history of the updated data sheet, for a detailed description of the changes.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02, SEM-DS-03

Reason

To include additional orderable part numbers for new product offerings (PF53 B revision / PF530xB) with design and package enhancements, as well as technical clarifications and corrections.

Identification of Affected Products

No change to existing PF530xA part numbers or products.
New PF530xB part numbers are identified with the silicon revision suffix "B" (e.g., MPF5300BMMALES), and the REV_ID register value 0x25.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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For existing PF530xA products: No Impact on form, fit, function, reliability or quality.
For new announced PF530xB product offerings, change compared to existing PF530xA product: form, fit, reliability/quality as described within the attached information.

Data Sheet Revision

A new data sheet will be issued

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

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